

Title (en)

ELECTRONIC SUPPORTS AND METHODS AND APPARATUS FOR FORMING APERTURES IN ELECTRONIC SUPPORTS

Title (de)

ELEKTRONISCHE TRÄGER UND VERFAHREN UND VORRICHTUNG ZUR HERSTELLUNG VON LÖCHERN IN ELEKTRONISCHEN TRÄGERN

Title (fr)

SUPPORTS ELECTRONIQUES ET PROCEDES ET APPAREIL DE FORMATION D'ORIFICES DANS DES SUPPORTS ELECTRONIQUES

Publication

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Application

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Abstract (en)

[origin: WO0163984A1] The present invention provides an electronic support (210) comprising: (A) a prepreg layer (214) comprising: (1) at least one reinforcement material (220); (2) at least one matrix material (216) in contact with at least a portion of the at least one reinforcement material (220); and (B) at least one layer (217) in contact with at least a portion (224) of at least one surface of the prepreg layer (214), the at least one layer (217) comprising at least one inorganic filler (218) and not greater than 25 weight percent of adhesive materials based on the total weight of at least one layer (217) on a total solids basis.

IPC 1-7

H05K 1/03

IPC 8 full level

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CPC (source: EP KR)

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Citation (search report)

See references of WO 0163984A1

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